

Product Name	Features
<p>ESPANEX M series [High Folding Endurance]</p>  <p>[Fine Pattern Circuit]</p> 	<p>[High Folding Endurance] ESPANEX M series is featured by new adhesiveless CCL with originally designed Polyimide, specialized in bending strength.</p>  <p>[Fine Pattern Circuit] ESPANEX M series is available for 30μm pitch or less (finer) pattern circuit by smooth and flat thin copper with Half etching technology.</p> 
<p>ESPANEX M series [Low Stiffness Type]</p> 	<p>M series (Low Stiffness Type) features a new adhesiveless Polyimide Thickness 20 μm Type, 12 μm Type and M series (Low Modulus Type) features a new adhesiveless CCL. This substrate benefits assembly in tight spaces due to its high flexibility.</p> 
<p>Liquid Crystal Polymer - CCL ESPANEX L series</p> <p>[High Frequency Devices]</p>  <p>[Property • Processability]</p> 	<p>LCP has high temperature capability, low CTE, low moisture absorption, Excellent electrical properties; especially at high frequencies and naturally flame resistance.</p> 